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Silicon NPN Epitaxial

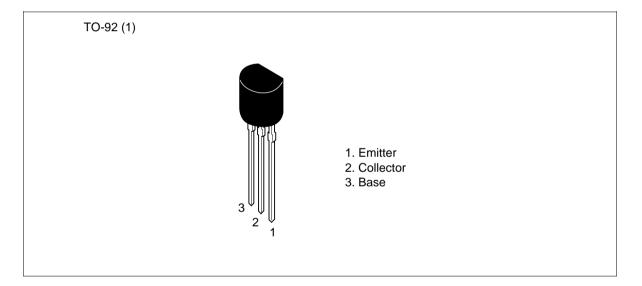


ADE-208-1078A (Z) 2nd. Edition Mar. 2001

Application

• Low frequency amplifier

Outline



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	2SC2853	2SC2854	Unit
Collector to base voltage	V _{CBO}	90	120	V
Collector to emitter voltage	V _{CEO}	90	120	V
Emitter to base voltage	V _{EBO}	5	5	V
Collector current	I _c	100	100	mA
Emitter current	IE	-100	-100	mA
Collector power dissipation	Pc	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

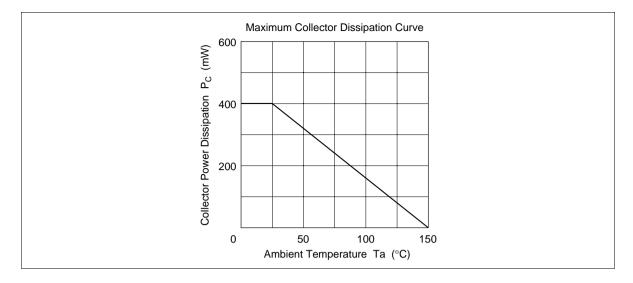
Electrical Characteristics (Ta = 25°C)

		2SC2853		2SC2854					
Item	Symbol	Min	Тур	Мах	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	90	_	_	120	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	90	—	—	120	—	—	V	$I_c = 1 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	—	—	5	—	—	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	—	—	0.1		—	0.1	μΑ	$V_{CB} = 70 \text{ V}, \text{ I}_{E} = 0$
Emitter cutoff current	I _{EBO}	—	—	0.1		—	0.1	μA	$V_{EB} = 2 V, I_{C} = 0$
DC current transfer ratio	h_{FE}^{*1}	250	—	800	250	—	800		$V_{ce} = 12 \text{ V}, \text{ I}_{c} = 2 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	0.05	0.10	—	0.05	0.10	V	$I_{c} = 10 \text{ mA}, I_{B} = 1 \text{ mA}^{*2}$
Base to emitter saturation voltage	$V_{\text{BE(sat)}}$	—	0.7	1.0	—	0.7	1.0	V	-
Gain bandwidth product	f _⊤	_	310	_		310	_	MHz	$V_{ce} = 6 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
Collector output capacitance	Cob	—	3	_	—	3	—	pF	$V_{_{CB}} = 10 \text{ V}, \text{ I}_{_{E}} = 0,$ f = 1 MHz
	100000					e 11			

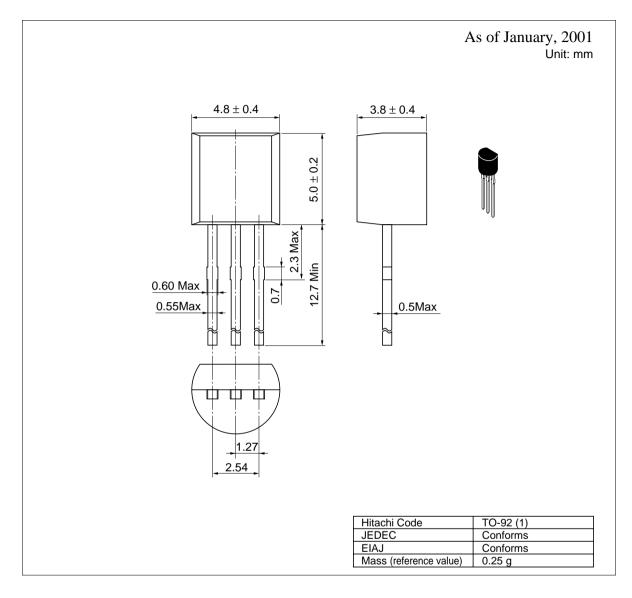
Notes: 1. The 2SC2853 and 2SC2854 are grouped by $h_{\mbox{\tiny FE}}$ as follows.

2. Pulse test **D E** 250 to 500 400 to 800

See characteristic curves of 2SC2855 and 2SC2856.



Package Dimensions



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